

YEA SHIN TECHNOLOGY CO., LTD

MB1S THRU MB10S

MINI SURFACE MOUNT GLASS PASSIVATED SINGLE-PHASE BRIDGE RECTIFIER VOLTAGE 100 to 1000Volts 0.8 Amperes CURRENT





FEATURES

Plastic material used carries Underwriters

Laboratory recognition 94V-0

Low leakage

Surge overload rating-- 30 amperes peak

Ideal for printed circuit board

Exceeds environmental standards of MIL-S-19500

High temperature soldering : 260°C / 10 seconds at terminals Pb free product at available : 99% Sn above meet RoHS

environment substance directive request

MECHANICAL DATA

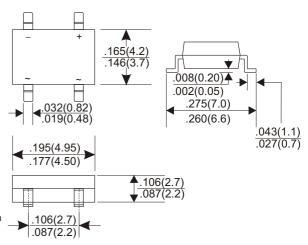
Case: Reliable low cost construction utilizing molded plastic technique results in . . .

inexpensive product

Terminals: Lead solderable per MIL-STD-202, Method 208. Polarity: Polarity symbols molded or marking on body.

Mounting Position: Any.

MDI Unit:inch(mm)



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz, Resistive or inductive load. For capacitive load, derate current by 20%

PARMETER	SYMBOLS	MB1S	MB2S	MB4S	MB6S	MB8S	MB10S	UNIT
Maximum Repetitive Peak Reverse Voltage	VRRM	100	200	400	600	800	1000	V
Maximum RMS Voltage	VRMS	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	VDC	100	200	400	600	800	1000	V
Maximum Average Forward Current	IAV	0.8						А
Peak Forward Surge Current:8.3ms single half sine - wave superimposed on rated load (JEDEC method)	IFSM	35						Α
I ² t Rating for fusing (t<8.35ms)	l ² t	5.084						A ² Sec
Maximum Forward Voltage Drop per Bridge Element at 0.8A	VF	1.0						V
Maximum DC Reverse Current TJ = 25 at Rate DC Blocking Voltage TJ =125	IR	5.0 500						μА
Typical Junction capacitance (Note 1)	CJ	25						pF
Typical thermal resistance (Note2)	R JA R JL	85 20						W
Operating, Storage Temperature Range	TJ, TSTG	-55 to +150						

NOTES:

- 1. Measured at 1.0 MHz and applied reverse voltage of 4.0 Volts
- 2. Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.5 X 0.5"(13 X 13mm) copper pads

DEVICE CHARACTERISTICS

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